

Munich, April 29, 2010

### **5th "Deep Dive" SMT Seminar:**

### **SIPLACE CA combines die-bonding and SMT placement to meet current trends in packaging of integrated circuits**

The "Deep Dive" SMT seminar hosted by suppliers like Siemens, Zevac, Haeraeus, Rehm, Christian Koenen and Kasper was recently held for the fifth time in Dresden. 150 guests attended the technical presentations on this year's topic "Current Trends in Packaging of Integrated Circuits". The audience was particularly interested in the SIPLACE team's presentation on the new SIPLACE CA, the world's first platform that combines die placement from wafers with classic SMT placement technology in a single machine. With the SIPLACE CA, manufacturers can save line space and money by eliminating the need for special die bonding processes and populating products with modern bare dies (flip-chip, die-attach) at high speed on a single line.

"The SIPLACE CA processes flip-chips from wafers at high speeds together with passive components from reels – this is really trailblazing. Accordingly, electronics manufacturers welcomed the machine with open arms, because the SIPLACE CA uncovers completely new possibilities in the production of modern, high-quality products," said Hubert Herzberg, Manager for the department Product Management Hardware at Siemens Electronics Assembly Systems (SEAS) about the positive response to his presentation on the new SIPLACE placement platform.

### **Up to 9,000 flip-chips per head per hour – directly from the wafer**

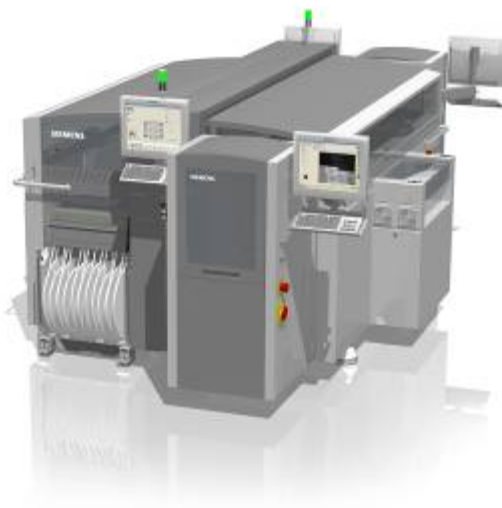
The SIPLACE CA is based on the SIPLACE X-Series with additional SIPLACE wafer systems (SWS) as feeders. Other special features include a flip unit, special vision systems and the linear flux dip unit (LDU). With this equipment, each SIPLACE Speedstar CP 20 head is able to place up to 9,000 flip-chips or 6,000 die-attach components per hour in sizes ranging from 0.8 to 18.7 millimeters with an accuracy of  $\pm 10 \mu\text{m}$ . The SIPLACE wafer system can handle different wafers; the wafers are replaced automatically, and the punch-out speed is programmable.

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The combination of bare-die and classic component processing in a single machine delivers a wide range of benefits for the manufacturer. Instead of having to run separate processes and lines, the SIPLACE CA allows the manufacturer to handle both on a single line with great flexibility. As a result, the performance increases while the space requirements decrease. "The yield will improve significantly as well with the new combination. Since the new process requires only one pass through the oven, there is less substrate warping, which makes for better circuits," explained Herzberg.

With its successful 2010 edition, the "Deep Dive" seminar series further enhanced its reputation as an exclusive SMT seminar. With 150 attendees, the event was fully booked, and for the first time late registrants had to place their names on a waiting list. The central location in Dresden and the high quality of the informative presentations over two days are obviously very much appreciated. The visitors were particularly impressed with the close relationship of the partners who aim to maximise the whole process for the benefit of the customers.



The new SIPLACE CA: The world's first platform, combining Die-Placement from wafer with classic SMT placement technology in a single machine.

For more information about SIPLACE, visit [www.siplace.com](http://www.siplace.com).

Please direct any reader inquiries to:  
Siemens  
Electronics Assembly Systems GmbH & Co. KG  
Susanne Oswald  
E-mail: [susanne.oswald@siemens.com](mailto:susanne.oswald@siemens.com)

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Susanne Oswald  
Rupert-Mayer-Strasse 44, D-81350 München

Tel.: +49 89 20800-26439; Fax: -24260  
E-mail: [susanne.oswald@siemens.com](mailto:susanne.oswald@siemens.com)  
Internet: [www.siplace.com](http://www.siplace.com)